

TECHNICAL SPECIFICATION

Grade	Basis Wt. Gr/m ²	Thickness Microns	Ply-Bond Ft.lb - J/m ²	Ring Crush Kgf	Bursting Kpa
Chip board	230 - 525	325 - 750	120 - 252	45 - 85	400 - 650
Super chip board	230 - 525	325 - 750	170 - 357	47 - 87	450 - 700
Core board B	230 - 525	325 - 750	200 - 420	50 - 100	475 - 750
Core board B+	230 - 525	325 - 750	225 - 473	52 - 102	500 - 800
Core board A30	260 - 525	340 - 700	250 - 525	65 - 120	525 - 850
Core board A31	260 - 525	340 - 700	300 - 630	70 - 125	550 - 925
Core board A32	260 - 525	340 - 700	350 - 735	80 - 135	575 - 950
Core board A42	260 - 500	340 - 650	405 - 850	85 - 140	600 - 975
Core board A51	260 - 500	340 - 650	475 - 1000	90 - 145	625 - 1000
PTK - 1	350 - 450	470 - 630	125 - 263	75 - 115	575 - 700
PTK - 2	350 - 450	470 - 630	150 - 315	80 - 120	625 - 800
PTK - 3	350 - 450	470 - 630	200 - 420	100 - 130	725 - 850
PTK - 3	350 - 450	470 - 630	225 - 473	125 - 160	775 - 900
PTK - 4	350 - 450	470 - 630	275 - 578	130 - 170	800 - 950
PTK - 5	350 - 450	470 - 630	325 - 683	135 - 175	850 - 1000

Cobb 60 sec. to customer request

SPECIFICATION AND PACKAGING

Moisture	7 +/- 1%		
Basis Wt.	+/- 4%	Roll Diameter	(1,000 -1,500) mm
Thickness	+/- 4%	Minimum Trim Accepted	2,200 mm
Ply-bond	+/- 10%	Min. Coil Width	90 mm
Packaging wrapped	Palletized, Strapped and Film		

Packaging: Palletized, Strapped and film Wrapped